

MC33201, MC33202, MC33204, NCV33202, NCV33204

PIN CONNECTIONS

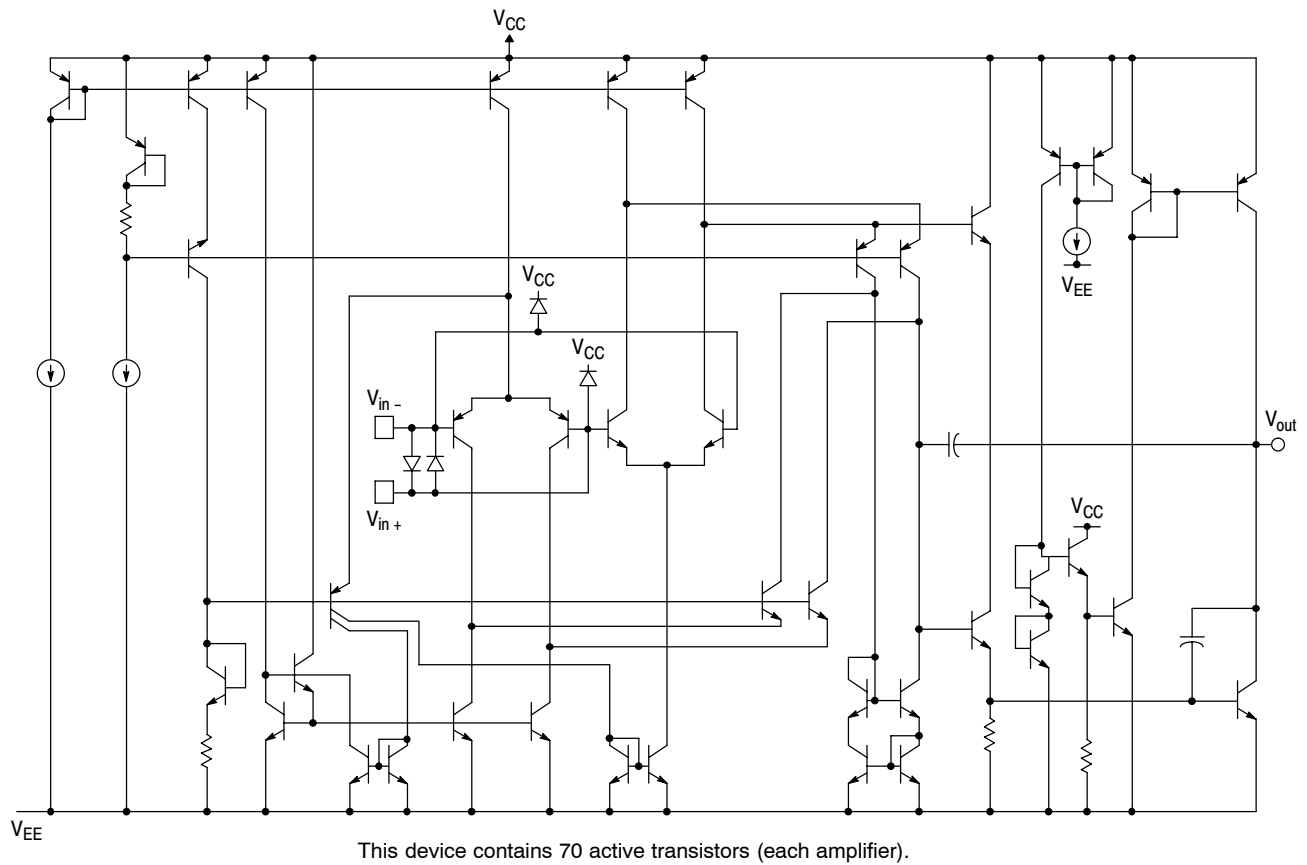
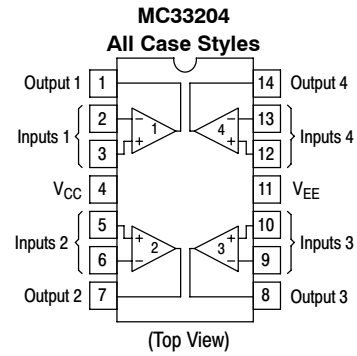
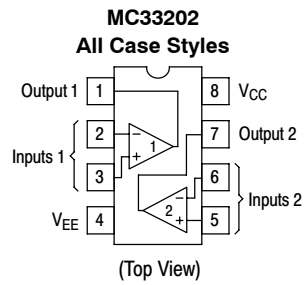
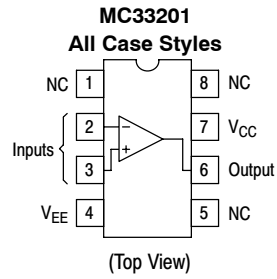


Figure 1. Circuit Schematic
(Each Amplifier)

MC33201, MC33202, MC33204, NCV33202, NCV33204

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage (V_{CC} to V_{EE})	V_S	+13	V
Input Differential Voltage Range	V_{IDR}	Note 1	V
Common Mode Input Voltage Range (Note 2)	V_{CM}	$V_{CC} + 0.5$ V to $V_{EE} - 0.5$ V	V
Output Short Circuit Duration	t_s	Note 3	sec
Maximum Junction Temperature	T_J	+150	°C
Storage Temperature	T_{stg}	- 65 to +150	°C
Maximum Power Dissipation	P_D	Note 3	mW

DC ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Characteristic	$V_{CC} = 2.0$ V	$V_{CC} = 3.3$ V	$V_{CC} = 5.0$ V	Unit
Input Offset Voltage $V_{IO} \text{ (max)}$ MC33201 MC33202, NCV33202 MC33204, NCV33204	± 8.0 ± 10 ± 12	± 8.0 ± 10 ± 12	± 6.0 ± 8.0 ± 10	mV
Output Voltage Swing V_{OH} ($R_L = 10$ k Ω) V_{OL} ($R_L = 10$ k Ω)	1.9 0.10	3.15 0.15	4.85 0.15	V_{min} V_{max}
Power Supply Current per Amplifier (I_D)	1.125	1.125	1.125	mA

Specifications at $V_{CC} = 3.3$ V are guaranteed by the 2.0 V and 5.0 V tests. $V_{EE} = \text{GND}$.

DC ELECTRICAL CHARACTERISTICS ($V_{CC} = +5.0$ V, $V_{EE} = \text{Ground}$, $T_A = 25^\circ\text{C}$, unless otherwise noted.)

Characteristic	Figure	Symbol	Min	Typ	Max	Unit
Input Offset Voltage ($V_{CM} = 0$ V to 0.5 V, $V_{CM} = 1.0$ V to 5.0 V) MC33201: $T_A = +25^\circ\text{C}$ MC33201: $T_A = -40^\circ$ to $+105^\circ\text{C}$ MC33201V: $T_A = -55^\circ$ to $+125^\circ\text{C}$ MC33202: $T_A = +25^\circ\text{C}$ MC33202: $T_A = -40^\circ$ to $+105^\circ\text{C}$ MC33202V: $T_A = -55^\circ$ to $+125^\circ\text{C}$ NCV33202V: $T_A = -55^\circ$ to $+125^\circ\text{C}$ (Note 4) MC33204: $T_A = +25^\circ\text{C}$ MC33204: $T_A = -40^\circ$ to $+105^\circ\text{C}$ MC33204V: $T_A = -55^\circ$ to $+125^\circ\text{C}$ NCV33204: $T_A = -55^\circ$ to $+125^\circ\text{C}$	3	$ V_{IO} $	- - - - - - - - - - - -	- - - - - - - - - - - -	6.0 9.0 13 8.0 11 14 14 10 13 17 17	mV
Input Offset Voltage Temperature Coefficient ($R_S = 50$ Ω) $T_A = -40^\circ$ to $+105^\circ\text{C}$ $T_A = -55^\circ$ to $+125^\circ\text{C}$	4	$\Delta V_{IO}/\Delta T$	- -	2.0 2.0	- -	$\mu\text{V}/^\circ\text{C}$
Input Bias Current ($V_{CM} = 0$ V to 0.5 V, $V_{CM} = 1.0$ V to 5.0 V) $T_A = +25^\circ\text{C}$ $T_A = -40^\circ$ to $+105^\circ\text{C}$ $T_A = -55^\circ$ to $+125^\circ\text{C}$	5, 6	$ I_{IB} $	- - -	80 100 -	200 250 500	nA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The differential input voltage of each amplifier is limited by two internal parallel back-to-back diodes. For additional differential input voltage range, use current limiting resistors in series with the input pins.
2. The input common mode voltage range is limited by internal diodes connected from the inputs to both supply rails. Therefore, the voltage on either input must not exceed either supply rail by more than 500 mV.
3. Power dissipation must be considered to ensure maximum junction temperature (T_J) is not exceeded. (See Figure 2)
4. NCV33202 and NCV33204 are qualified for automotive use.

MC33201, MC33202, MC33204, NCV33202, NCV33204

DC ELECTRICAL CHARACTERISTICS (cont.) ($V_{CC} = +5.0\text{ V}$, $V_{EE} = \text{Ground}$, $T_A = 25^\circ\text{C}$, unless otherwise noted.)

Characteristic	Figure	Symbol	Min	Typ	Max	Unit
Input Offset Current ($V_{CM} = 0\text{ V to } 5.0\text{ V}$, $V_{CM} = 1.0\text{ V to } 5.0\text{ V}$) $T_A = +25^\circ\text{C}$ $T_A = -40^\circ\text{ to } +105^\circ\text{C}$ $T_A = -55^\circ\text{ to } +125^\circ\text{C}$	–	$ I_{IO} $	– – –	5.0 10 –	50 100 200	nA
Common Mode Input Voltage Range	–	V_{ICR}	V_{EE}	–	V_{CC}	V
Large Signal Voltage Gain ($V_{CC} = +5.0\text{ V}$, $V_{EE} = -5.0\text{ V}$) $R_L = 10\text{ k}\Omega$ $R_L = 600\text{ }\Omega$	7	A_{VOL}	50 25	300 250	– –	kV/V
Output Voltage Swing ($V_{ID} = \pm 0.2\text{ V}$) $R_L = 10\text{ k}\Omega$ $R_L = 10\text{ k}\Omega$ $R_L = 600\text{ }\Omega$ $R_L = 600\text{ }\Omega$	8, 9, 10	V_{OH} V_{OL} V_{OH} V_{OL}	4.85 – 4.75 –	4.95 0.05 4.85 0.15	– 0.15 – 0.25	V
Common Mode Rejection ($V_{in} = 0\text{ V to } 5.0\text{ V}$)	11	CMR	60	90	–	dB
Power Supply Rejection Ratio $V_{CC}/V_{EE} = 5.0\text{ V/GND to } 3.0\text{ V/GND}$	12	PSRR	500	25	–	$\mu\text{V/V}$
Output Short Circuit Current (Source and Sink)	13, 14	I_{SC}	50	80	–	mA
Power Supply Current per Amplifier ($V_O = 0\text{ V}$) $T_A = -40^\circ\text{ to } +105^\circ\text{C}$ $T_A = -55^\circ\text{ to } +125^\circ\text{C}$	15	I_D	– –	0.9 0.9	1.125 1.125	mA

AC ELECTRICAL CHARACTERISTICS ($V_{CC} = +5.0\text{ V}$, $V_{EE} = \text{Ground}$, $T_A = 25^\circ\text{C}$, unless otherwise noted.)

Characteristic	Figure	Symbol	Min	Typ	Max	Unit
Slew Rate ($V_S = \pm 2.5\text{ V}$, $V_O = -2.0\text{ V to } +2.0\text{ V}$, $R_L = 2.0\text{ k}\Omega$, $A_V = +1.0$)	16, 26	SR	0.5	1.0	–	V/ μs
Gain Bandwidth Product ($f = 100\text{ kHz}$)	17	GBW	–	2.2	–	MHz
Gain Margin ($R_L = 600\text{ }\Omega$, $C_L = 0\text{ pF}$)	20, 21, 22	A_M	–	12	–	dB
Phase Margin ($R_L = 600\text{ }\Omega$, $C_L = 0\text{ pF}$)	20, 21, 22	ϕ_M	–	65	–	Deg
Channel Separation ($f = 1.0\text{ Hz to } 20\text{ kHz}$, $A_V = 100$)	23	CS	–	90	–	dB
Power Bandwidth ($V_O = 4.0\text{ V}_{pp}$, $R_L = 600\text{ }\Omega$, $\text{THD} \leq 1\%$)		BW_P	–	28	–	kHz
Total Harmonic Distortion ($R_L = 600\text{ }\Omega$, $V_O = 1.0\text{ V}_{pp}$, $A_V = 1.0$) $f = 1.0\text{ kHz}$ $f = 10\text{ kHz}$	24	THD	– –	0.002 0.008	– –	%
Open Loop Output Impedance ($V_O = 0\text{ V}$, $f = 2.0\text{ MHz}$, $A_V = 10$)		$ Z_O $	–	100	–	Ω
Differential Input Resistance ($V_{CM} = 0\text{ V}$)		R_{in}	–	200	–	k Ω
Differential Input Capacitance ($V_{CM} = 0\text{ V}$)		C_{in}	–	8.0	–	pF
Equivalent Input Noise Voltage ($R_S = 100\text{ }\Omega$) $f = 10\text{ Hz}$ $f = 1.0\text{ kHz}$	25	e_n	– –	25 20	– –	nV/ $\sqrt{\text{Hz}}$
Equivalent Input Noise Current $f = 10\text{ Hz}$ $f = 1.0\text{ kHz}$	25	i_n	– –	0.8 0.2	– –	pA/ $\sqrt{\text{Hz}}$

MC33201, MC33202, MC33204, NCV33202, NCV33204

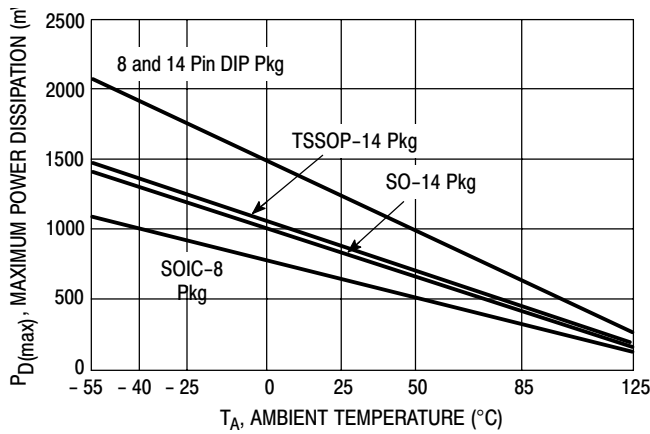


Figure 2. Maximum Power Dissipation versus Temperature

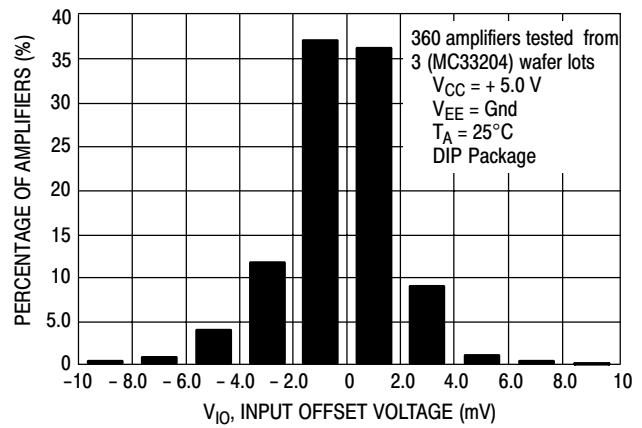


Figure 3. Input Offset Voltage Distribution

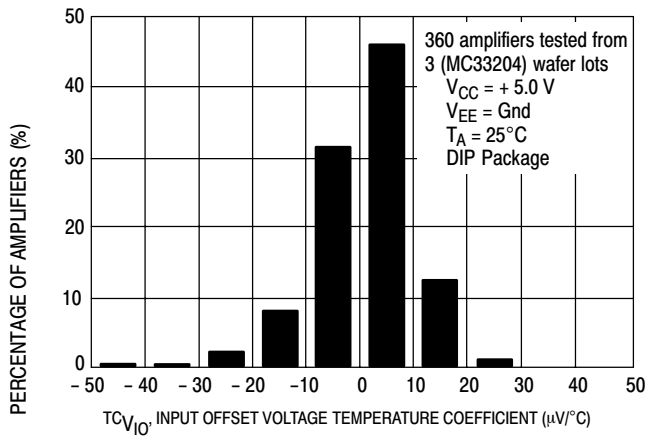


Figure 4. Input Offset Voltage Temperature Coefficient Distribution

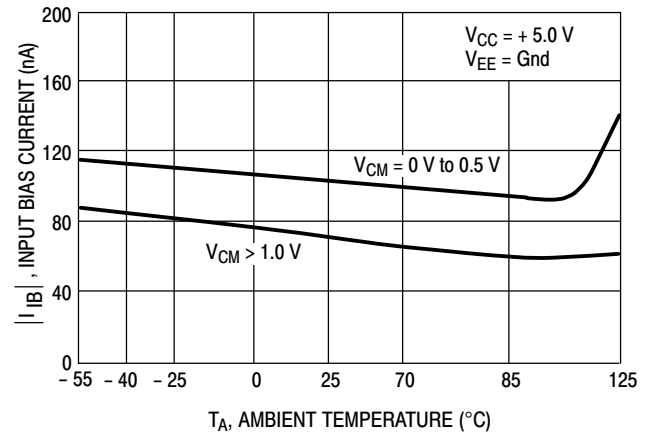


Figure 5. Input Bias Current versus Temperature

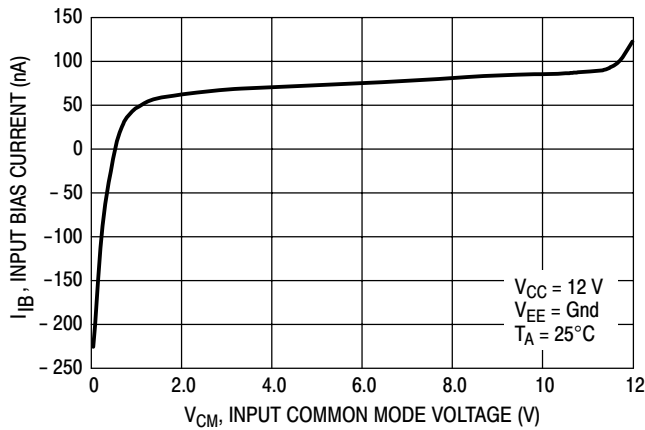


Figure 6. Input Bias Current versus Common Mode Voltage

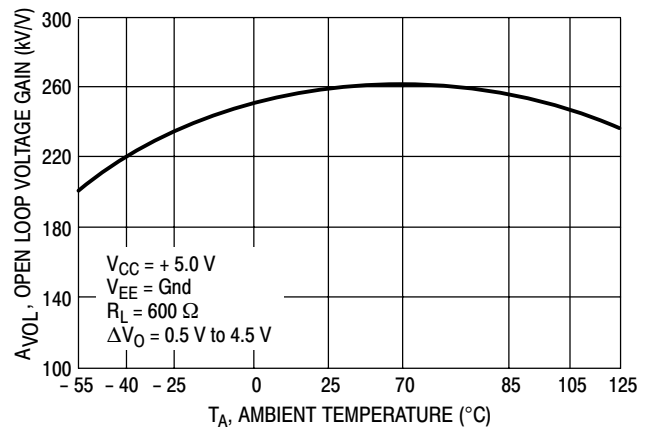


Figure 7. Open Loop Voltage Gain versus Temperature

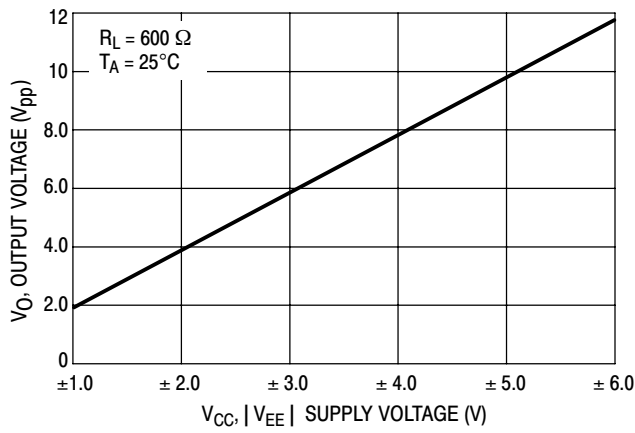


Figure 8. Output Voltage Swing versus Supply Voltage

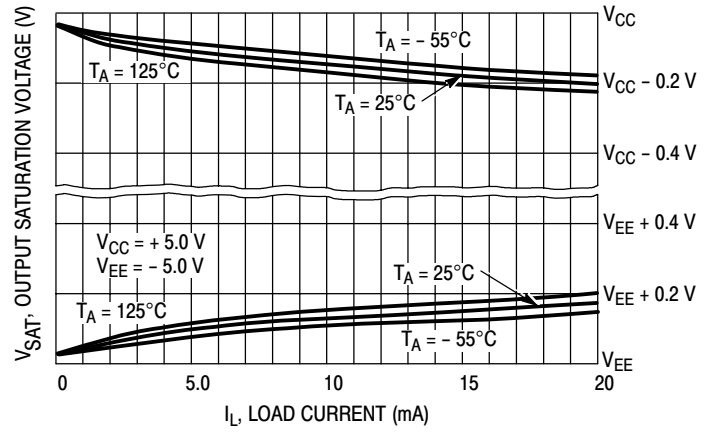


Figure 9. Output Saturation Voltage versus Load Current

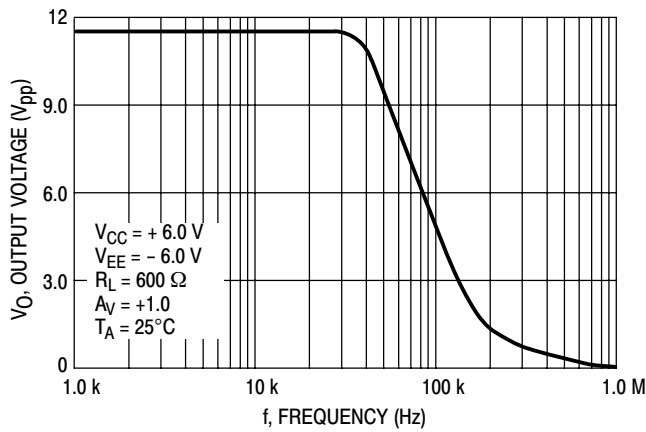


Figure 10. Output Voltage versus Frequency

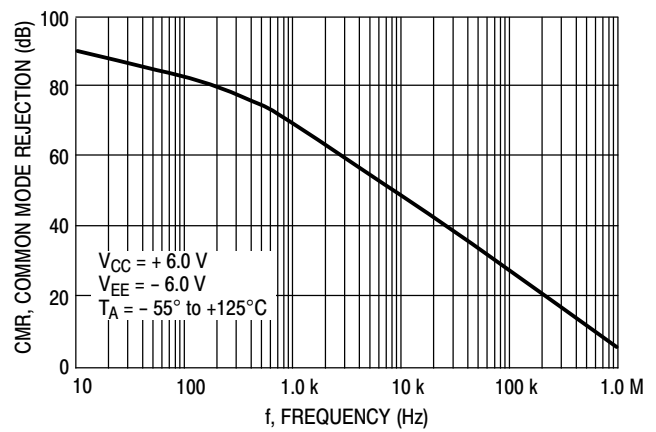


Figure 11. Common Mode Rejection versus Frequency

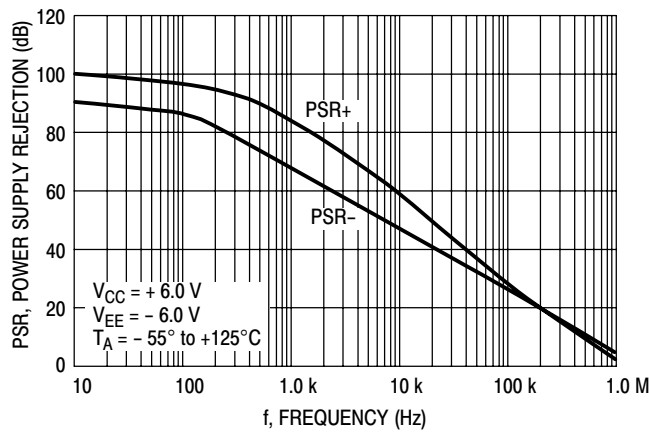


Figure 12. Power Supply Rejection versus Frequency

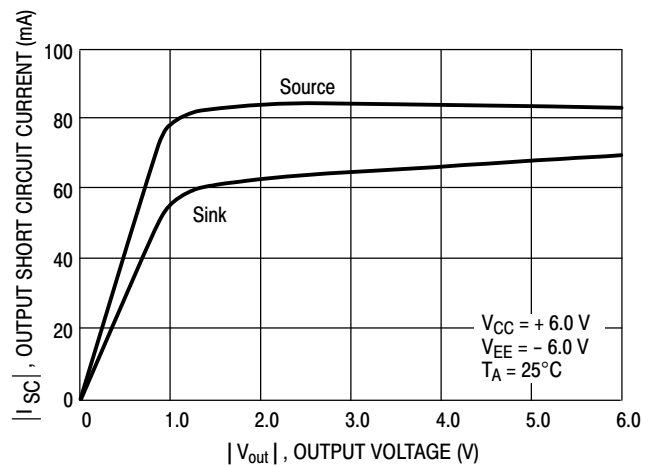


Figure 13. Output Short Circuit Current versus Output Voltage

MC33201, MC33202, MC33204, NCV33202, NCV33204

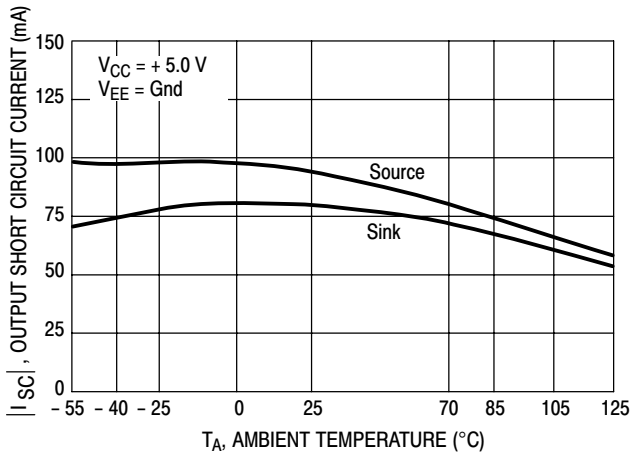


Figure 14. Output Short Circuit Current versus Temperature

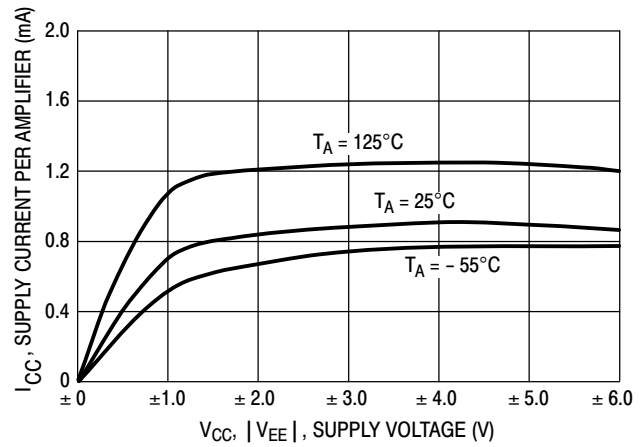


Figure 15. Supply Current per Amplifier versus Supply Voltage with No Load

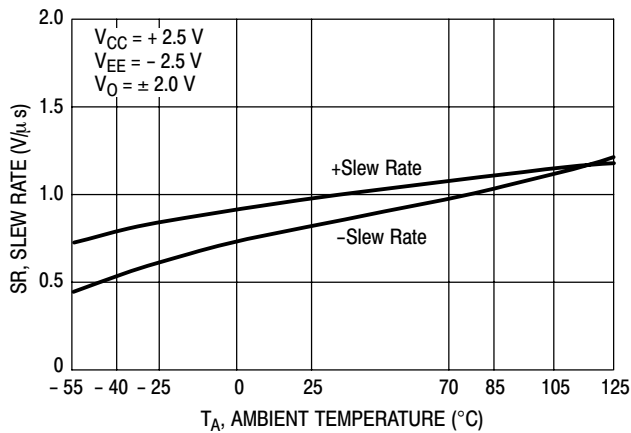


Figure 16. Slew Rate versus Temperature

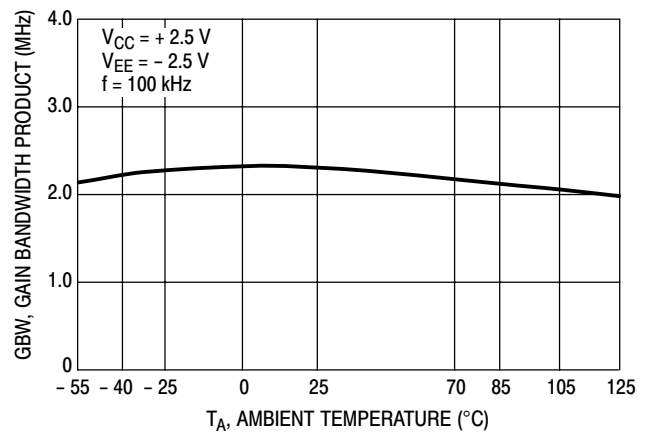


Figure 17. Gain Bandwidth Product versus Temperature

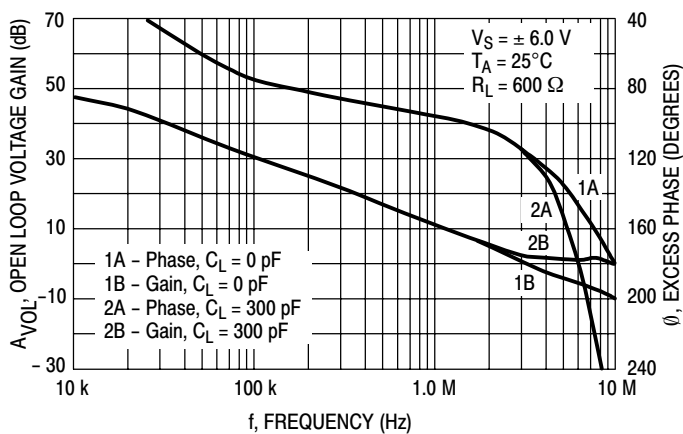


Figure 18. Voltage Gain and Phase versus Frequency

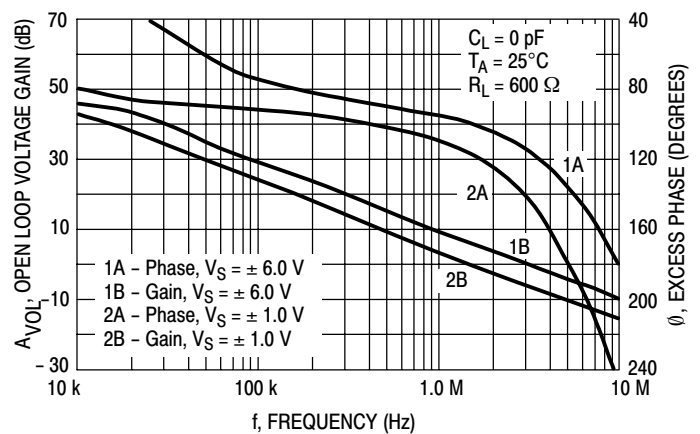


Figure 19. Voltage Gain and Phase versus Frequency

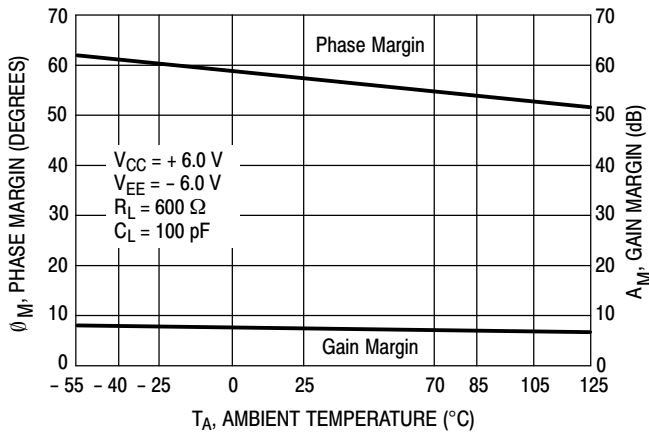


Figure 20. Gain and Phase Margin versus Temperature

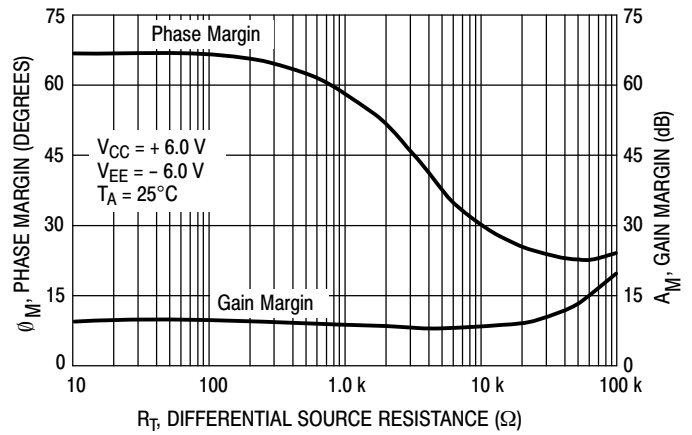


Figure 21. Gain and Phase Margin versus Differential Source Resistance

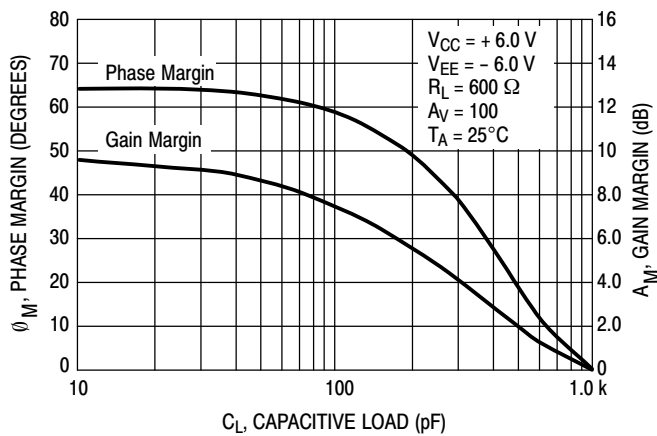


Figure 22. Gain and Phase Margin versus Capacitive Load

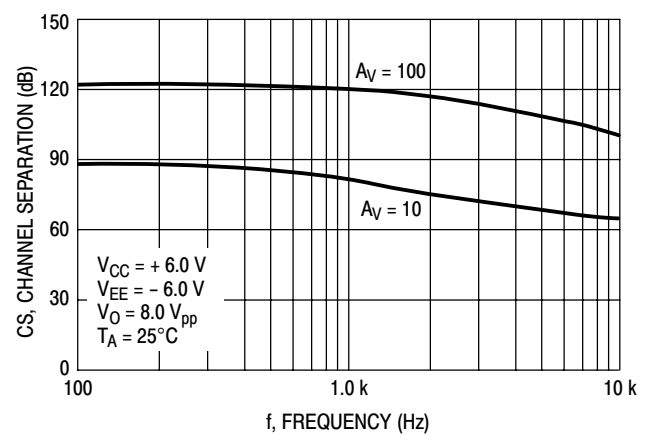


Figure 23. Channel Separation versus Frequency

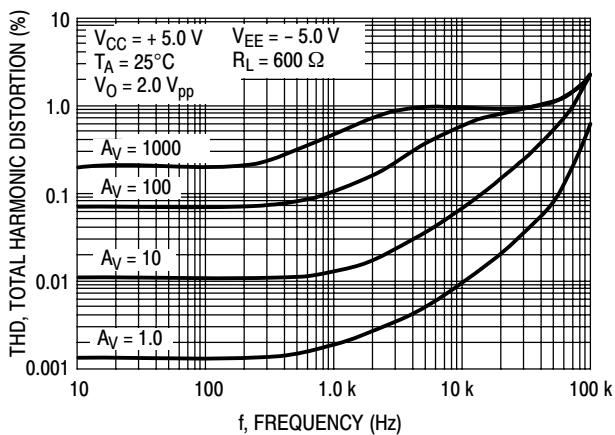


Figure 24. Total Harmonic Distortion versus Frequency

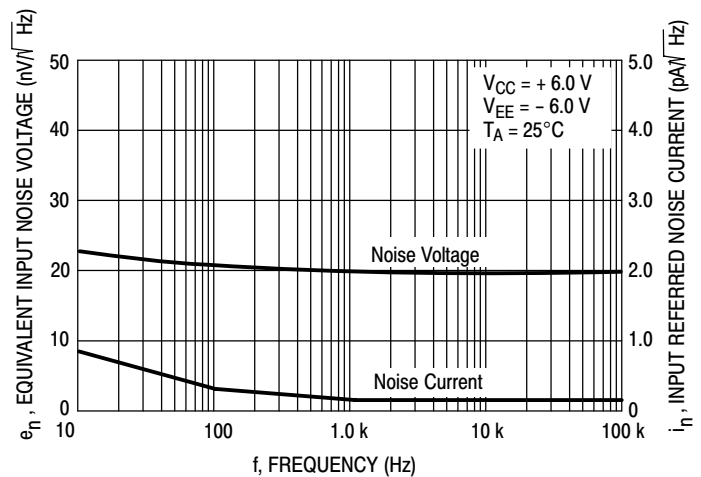


Figure 25. Equivalent Input Noise Voltage and Current versus Frequency

DETAILED OPERATING DESCRIPTION

General Information

The MC33201/2/4 family of operational amplifiers are unique in their ability to swing rail-to-rail on both the input and the output with a completely bipolar design. This offers low noise, high output current capability and a wide common mode input voltage range even with low supply voltages. Operation is guaranteed over an extended temperature range and at supply voltages of 2.0 V, 3.3 V and 5.0 V and ground.

Since the common mode input voltage range extends from V_{CC} to V_{EE} , it can be operated with either single or split voltage supplies. The MC33201/2/4 are guaranteed not to latch or phase reverse over the entire common mode range, however, the inputs should not be allowed to exceed maximum ratings.

Circuit Information

Rail-to-rail performance is achieved at the input of the amplifiers by using parallel NPN-PNP differential input stages. When the inputs are within 800 mV of the negative rail, the PNP stage is on. When the inputs are more than 800 mV greater than V_{EE} , the NPN stage is on. This switching of input pairs will cause a reversal of input bias currents (see Figure 6). Also, slight differences in offset voltage may be noted between the NPN and PNP pairs. Cross-coupling techniques have been used to keep this change to a minimum.

In addition to its rail-to-rail performance, the output stage is current boosted to provide 80 mA of output current, enabling the op amp to drive 600 Ω loads. Because of this high output current capability, care should be taken not to exceed the 150°C maximum junction temperature.

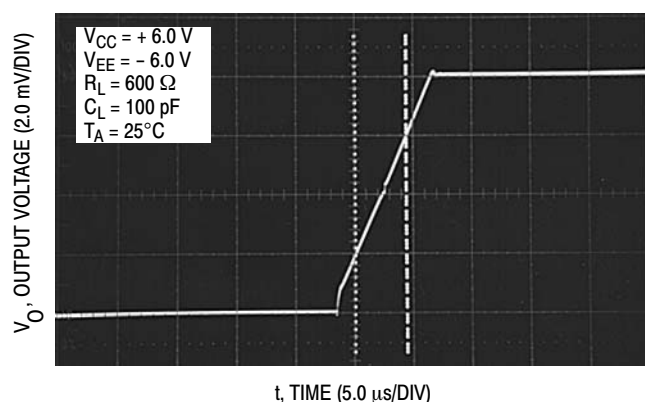


Figure 26. Noninverting Amplifier Slew Rate

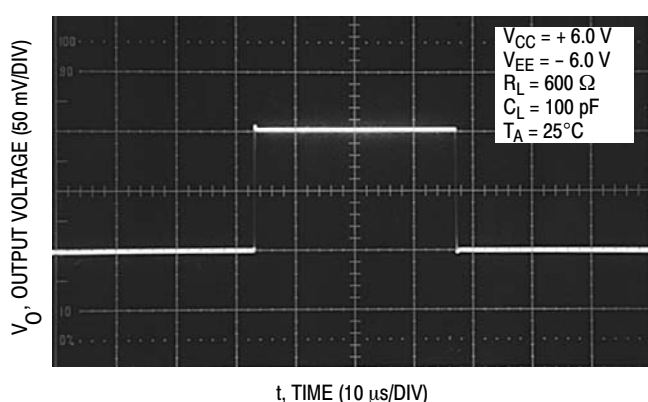


Figure 27. Small Signal Transient Response

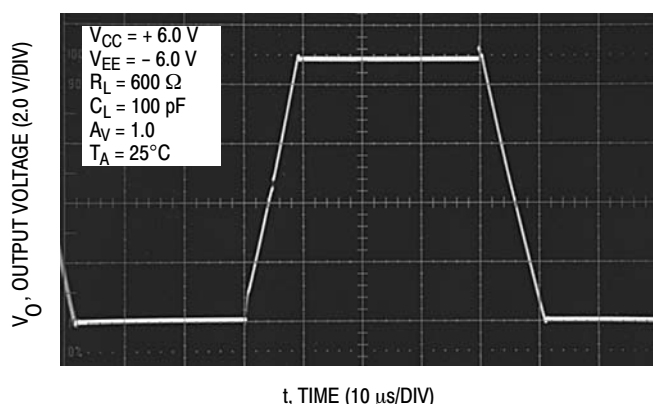


Figure 28. Large Signal Transient Response

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to ensure proper solder connection interface

between the board and the package. With the correct pad geometry, the packages will self-align when subjected to a solder reflow process.

MC33201, MC33202, MC33204, NCV33202, NCV33204

ORDERING INFORMATION

Operational Amplifier Function	Device	Operating Temperature Range	Package	Shipping†
Single	MC33201D	$T_A = -40^{\circ}$ to $+105^{\circ}\text{C}$	SOIC-8	98 Units / Rail
	MC33201DG		SOIC-8 (Pb-Free)	
	MC33201DR2		SOIC-8	2500 / Tape & Reel
	MC33201DR2G		SOIC-8 (Pb-Free)	
	MC33201P		PDIP-8	50 Units / Rail
	MC33201PG		PDIP-8 (Pb-Free)	
	MC33201VD	$T_A = -55^{\circ}$ to 125°C	SOIC-8	98 Units / Rail
	MC33201VDG		SOIC-8 (Pb-Free)	
Dual	MC33202D	$T_A = -40^{\circ}$ to $+105^{\circ}\text{C}$	SOIC-8	98 Units / Rail
	MC33202DG		SOIC-8 (Pb-Free)	
	MC33202DR2		SOIC-8	2500 / Tape & Reel
	MC33202DR2G		SOIC-8 (Pb-Free)	
	MC33202DMR2		Micro-8	4000 / Tape & Reel
	MC33202DMR2G		Micro-8 (Pb-Free)	
	MC33202P		PDIP-8	50 Units / Rail
	MC33202PG		PDIP-8 (Pb-Free)	
	MC33202VD	$T_A = -55^{\circ}$ to 125°C	SOIC-8	98 Units / Rail
	MC33202VDG		SOIC-8 (Pb-Free)	
	MC33202VDR2		SOIC-8	2500 / Tape & Reel
	MC33202VDR2G		SOIC-8 (Pb-Free)	
	NCV33202VDR2*		SOIC-8	
	NCV33202VDR2G*		SOIC-8 (Pb-Free)	
	MC33202VP		PDIP-8	50 Units / Rail
	MC33202VPG		PDIP-8 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NCV33202 and NCV33204 are qualified for automotive use.

MC33201, MC33202, MC33204, NCV33202, NCV33204

ORDERING INFORMATION (continued)

Operational Amplifier Function	Device	Operating Temperature Range	Package	Shipping [†]
Quad	MC33204D	T _A = -40 ° to +105°C	SO-14	55 Units / Rail
	MC33204DG		SO-14 (Pb-Free)	
	MC33204DR2		SO-14	2500 / Tape & Reel
	MC33204DR2G		SO-14 (Pb-Free)	
	MC33204DTB		TSSOP-14*	96 Units / Rail
	MC33204DTBG		TSSOP-14*	
	MC33204DTBR2		TSSOP-14*	2500 / Tape & Reel
	MC33204DTBR2G		TSSOP-14*	
	MC33204P		PDIP-14	25 Units / Rail
	MC33204PG		PDIP-14 (Pb-Free)	
	MC33204VD	T _A = -55° to 125°C	SO-14	55 Units / Rail
	MC33204VDG		SO-14 (Pb-Free)	
	MC33204VDR2		SO-14	2500 / Tape & Reel
	MC33204VDR2G		SO-14 (Pb-Free)	
	NCV33204DR2**		SO-14	
	NCV33204DR2G**		SO-14 (Pb-Free)	
	NCV33204DTBR2**		TSSOP-14*	
	NCV33204DTBR2G**		TSSOP-14*	
	MC33204VP		PDIP-14	25 Units / Rail
	MC33204VPG		PDIP-14 (Pb-Free)	

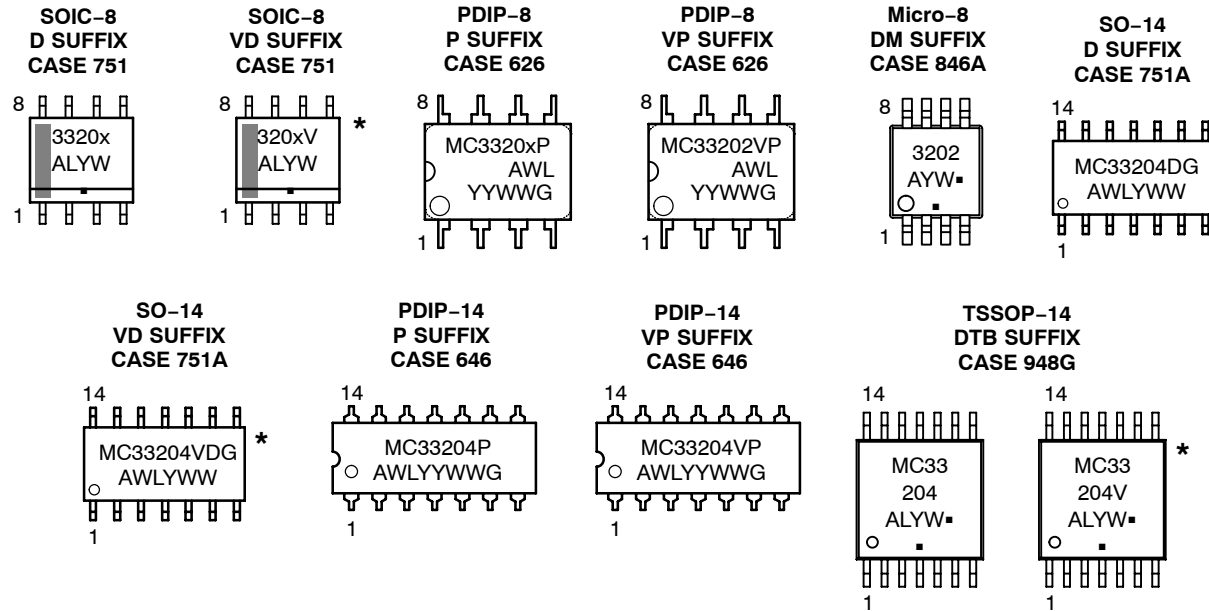
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

**NCV33202 and NCV33204 are qualified for automotive use.

MC33201, MC33202, MC33204, NCV33202, NCV33204

MARKING DIAGRAMS

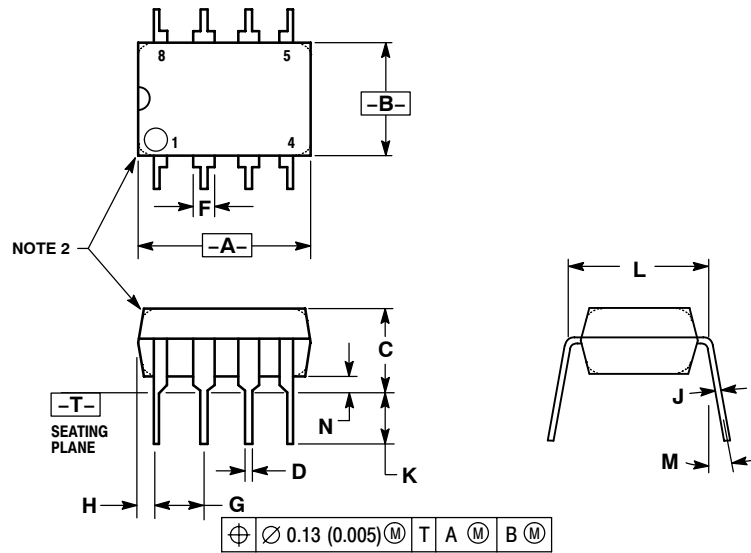


x = 1 or 2
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package
▪ = Pb-Free Package
(Note: Microdot may be in either location)
*This marking diagram applies to NCV3320x

MC33201, MC33202, MC33204, NCV33202, NCV33204

PACKAGE DIMENSIONS

PDIP-8
P, VP SUFFIX
CASE 626-05
ISSUE L

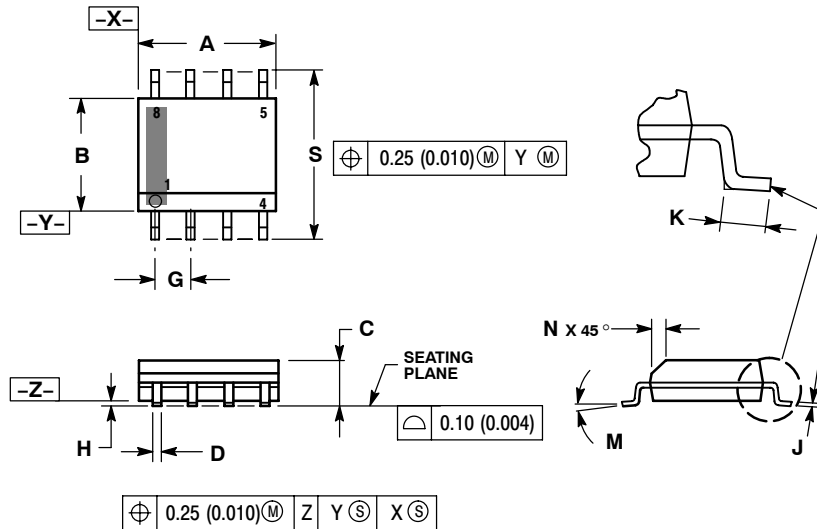


NOTES:

1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	---	10°	---	10°
N	0.76	1.01	0.030	0.040

PACKAGE DIMENSIONS

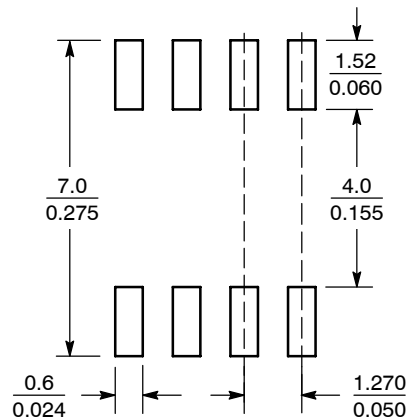
SOIC-8 NB
CASE 751-07
ISSUE AH

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

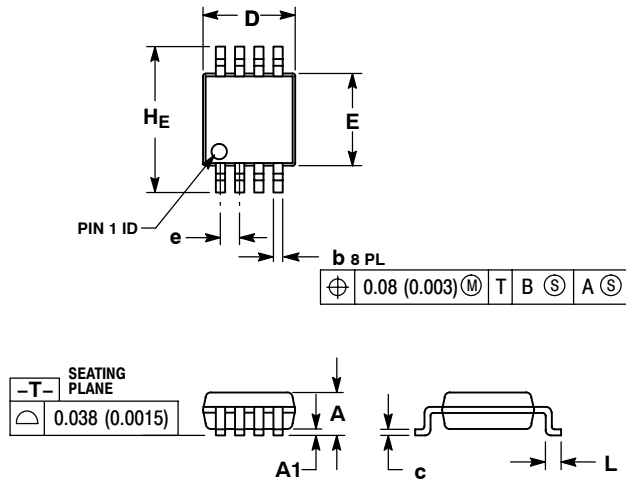
SCALE 6:1 $\left(\frac{\text{mm}}{\text{inches}} \right)$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC33201, MC33202, MC33204, NCV33202, NCV33204

PACKAGE DIMENSIONS

Micro8 DM SUFFIX CASE 846A-02 ISSUE G

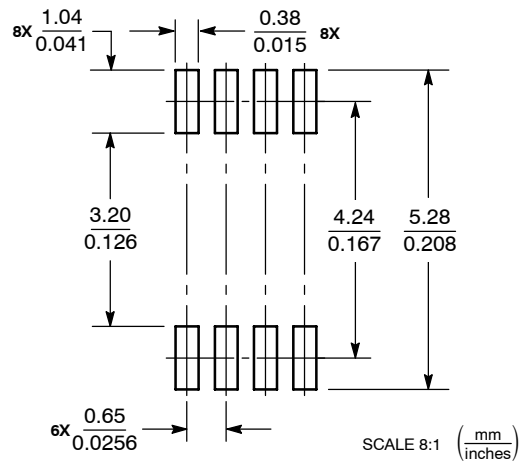


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	---	---	1.10	---	---	0.043
A1	0.05	0.08	0.15	0.002	0.003	0.006
b	0.25	0.33	0.40	0.010	0.013	0.016
c	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
e	0.65 BSC			0.026 BSC		
L	0.40	0.55	0.70	0.016	0.021	0.028
HE	4.75	4.90	5.05	0.187	0.193	0.199

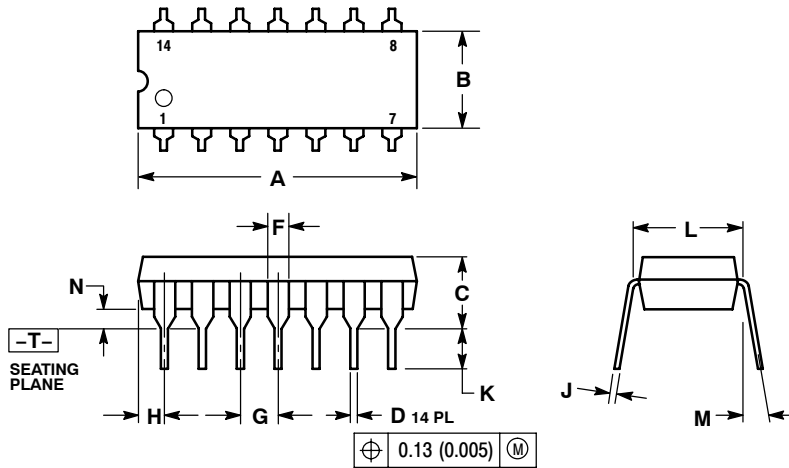
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

PDIP-14
CASE 646-06
ISSUE P



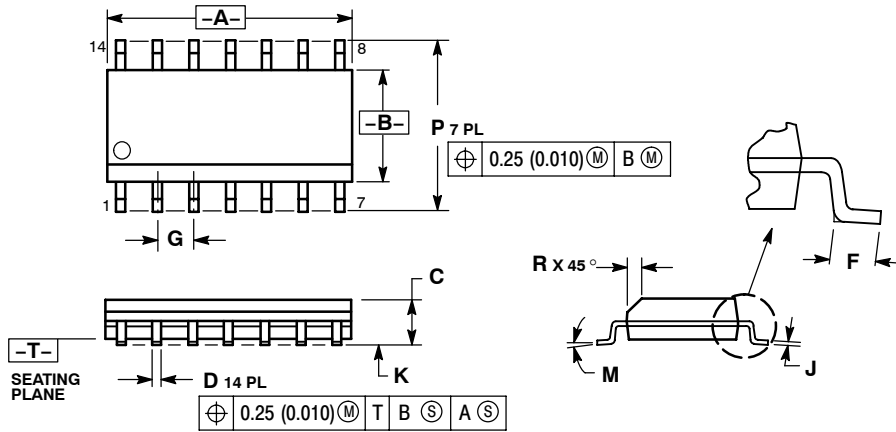
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10 °	---	10 °
N	0.015	0.039	0.38	1.01

MC33201, MC33202, MC33204, NCV33202, NCV33204

SOIC-14
CASE 751A-03
ISSUE H

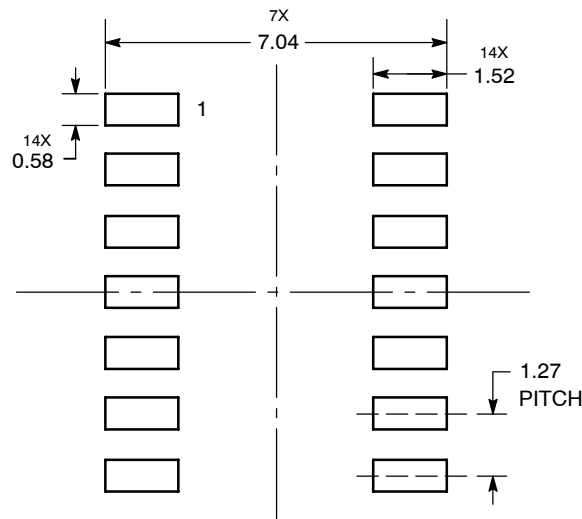


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

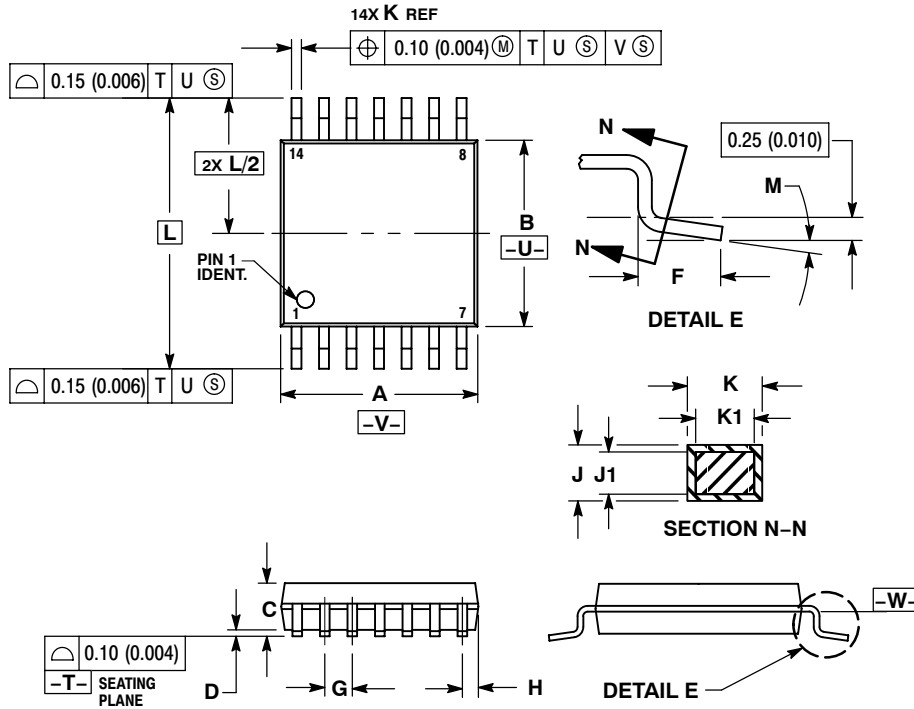
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

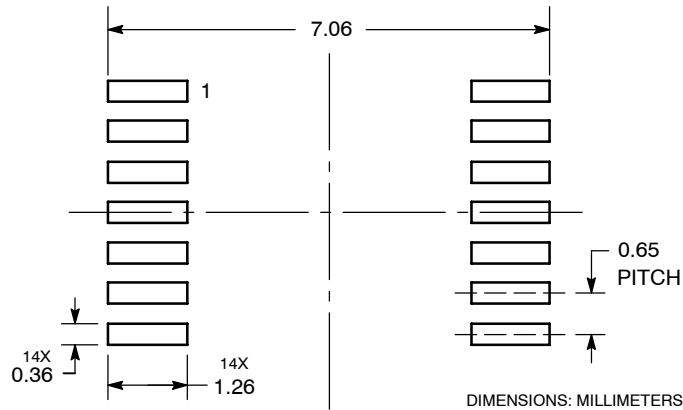
TSSOP-14
CASE 948G-01
ISSUE B

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 ° 8 °		0 ° 8 °	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Micro8 is a trademark of International Rectifier.

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada

Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local
Sales Representative